## nexperia

## **Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Suppli	ier	User Part Number						
Nexperia B.V.		74AXP1G00GM						
Part D	Description: Single 2-input I	NAND gate						
Pro	nction Family: AXP ocess family: C050 ckage family: XSON							
JESD4	7 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects		
# 1	<b>TEST</b> Pre- and Post-Stress	Tamb = 25 °C	N/A	see below	all parts	see		
<i>π</i> <b>⊥</b>	Electrical Test			See Delow		below		
# 2	<b>PC</b> Preconditioning	JESD22-A113 MSL 1	N/A	1007	27163	0		
# 5a	HTOL EFR High Temperature Operating Life Extrinsic	JESD22-A108 Tj = 150°C $V_{CCMAX} \le V \le 1.2*V_{CCMAX}$	48 hours or 168 hours	54	12492	0		
# 5b	HTOL IFR High Temperature Operating Life Intrinsic	JESD22-A108 Tj = 150°C $V_{CCMAX} \le V \le 1.2*V_{CCMAX}$	≥500 hours	33	2913	0		
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to 150°C	≥500 cycles	548	15036	0		
# 9	uHAST / HAST unbiased or biased High Accelerated Stress Test	JESD22-A101 Tamb = 130 °C, RH = 85%, V = V <sub>CCMAX</sub>	96 hours	520	12127	0		

## **Calculation of PPM, FIT and MTTF**

Test considered for PPM calculation: High Temperature Operating LifeTest Extrinsic (HTOL EFR, Test # 5a above) Test considered for FIT and MTTF calculations: High Temperature Operating LifeTest Intrinsic(HTOL IFR, Test # 5b above)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Product Family	Package Family	Quantity	Rejects	Extrinsic Failure Rate (PPM)	Intrinsic Failure Rate (FIT)	MTTF (hrs)
AXP	XSON	2913	0	74	1.4	7.57 E+08

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